

**AMENDMENTS TO THE CLAIMS**

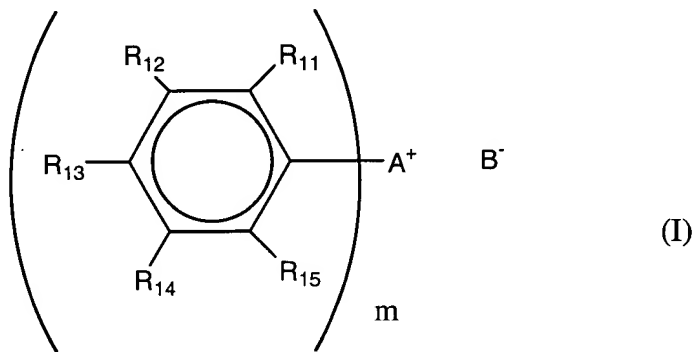
**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

**Please enter the following amended claims:**

1. (Twice Amended) A positive radiation-sensitive composition comprising:
- (a) a resin whose solubility in an alkali developer increases by the action of an acid;
  - (b) a compound that generates a carboxylic acid having a molecular weight of 100 or less upon irradiation with an actinic ray or a radiant ray;
  - (c) a surfactant; and
  - (d) a solvent,

wherein compound (b) is present in an amount of from 1 to 20 wt% based upon the solid contents, and the compound (b) is a compound represented by the following formula (I):



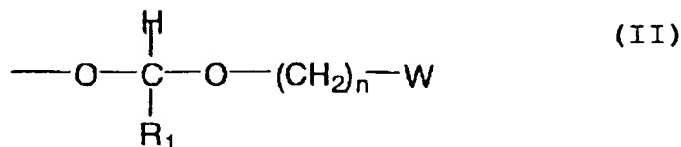
wherein  $R_{11}$ ,  $R_{12}$ ,  $R_{13}$ ,  $R_{14}$  and  $R_{15}$  each independently represents a hydrogen atom, a straight chain, branched or cyclic alkyl group, a straight chain, branched or cyclic alkoxy group, a

hydroxyl group, a halogen atom, or -S-R<sub>0</sub>; R<sub>0</sub> represents a straight chain, branched or cyclic alkyl group, or an aryl group, A<sup>+</sup> represents S<sup>+</sup> or I<sup>+</sup>; B<sup>-</sup> represents CH<sub>3</sub>COO<sup>-</sup>, C<sub>2</sub>H<sub>5</sub>COO<sup>-</sup> or C<sub>3</sub>H<sub>7</sub>COO<sup>-</sup>; and m represents 2 or 3.

2. (original): The positive radiation-sensitive composition as claimed in claim 1, which further comprises (b') a compound that generates a sulfonic acid upon irradiation with an actinic ray or a radiant ray.

3. (canceled).

4. (original): The positive radiation-sensitive composition as claimed in claim 1, wherein the resin (a) has an acid-decomposable group represented by the following formula (II):



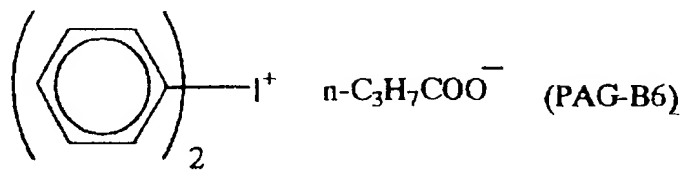
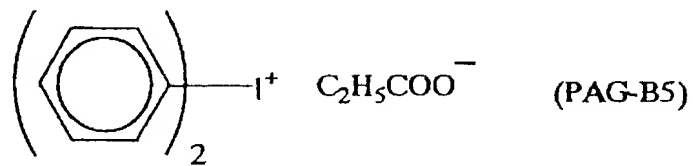
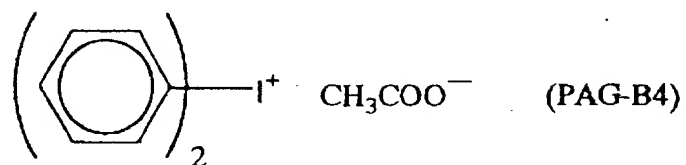
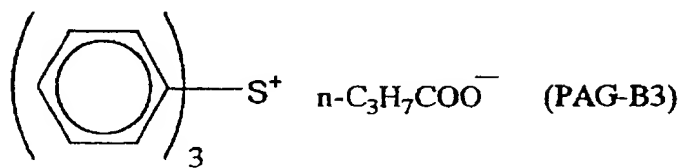
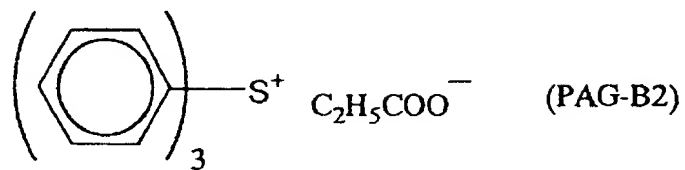
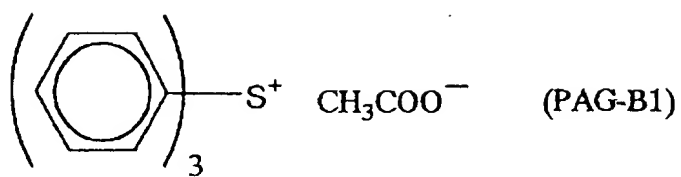
wherein R<sub>1</sub> represents an alkyl group having from 1 to 4 carbon atoms; W represents an amino group, an ammonium group, a mercapto group, a substituted or unsubstituted aryl group, a substituted or unsubstituted cycloalkyl group, or an organic group containing (i) at least one atom selected from the group consisting of an oxygen atom, a nitrogen atom, a sulfur atom, a

phosphorus atom and a silicon atom, and (ii) at least one carbon atom; and n represents a natural number of from 1 to 4.

5. (original): The positive radiation-sensitive composition as claimed in claim 1, wherein the resin (a) is a resin in which phenolic hydroxyl groups in an alkali-soluble resin are at least partly protected with the acid-decomposable group represented by the formula (II).

6. (original): The positive radiation-sensitive composition as claimed in claim 1, which further comprises an organic basic compound.

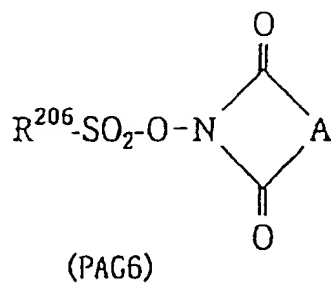
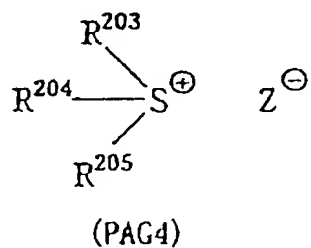
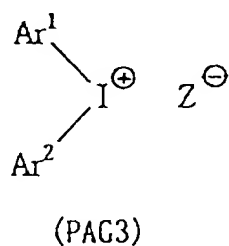
7. (original): The positive radiation-sensitive composition as claimed in claim 1, wherein the compound (b) is at least one compound selected from the group consisting of the following (PAG-B1) to (PAG-B6):



8. (currently amended): The positive radiation-sensitive composition as claimed in claim 7, wherein the compound (b) is at least one compound selected from the group consisting of the above (PAG-B1) and (PAG-B4):

9. (canceled).

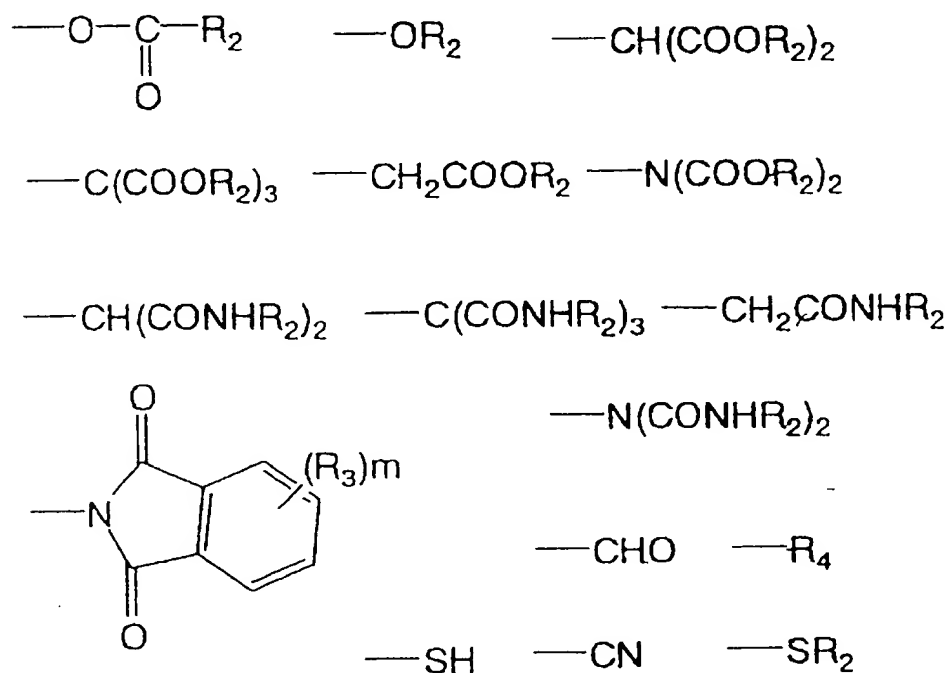
10. (original): The positive radiation-sensitive composition as claimed in claim 2, wherein the compound (b') is a compound represented by the following formula (PAG3), (PAG4) or (PAG6):



wherein  $Ar^1$  and  $Ar^2$  each independently represents a substituted or unsubstituted aryl group;  
 $R^{203}$ ,  $R^{204}$  and  $R^{205}$  each independently represents a substituted or unsubstituted alkyl or aryl  
group;  $R^{206}$  represents a substituted or unsubstituted alkyl or aryl group; A represents a  
substituted or unsubstituted alkylene, alkenylene or arylene group.

11. (original):The positive radiation-sensitive composition as claimed in claim 2,  
which contains the compound (b') in an amount of from 1 to 20 wt% based on the solid contents.

12. (original):The positive radiation-sensitive composition as claimed in claim 4,  
wherein W of said formula (II) is a group represented by the following formula:



wherein R<sub>2</sub> represents a hydrogen atom, a straight chain, branched or cyclic alkyl group having from 1 to 6 carbon atoms, a straight chain, branched or cyclic alkenyl group having from 2 to 6 carbon atoms, a substituted or unsubstituted aryl group, or a substituted or unsubstituted aralkyl group; R<sub>3</sub> represents a hydrogen atom, a straight chain, branched or cyclic alkyl group having from 1 to 6 carbon atoms, a straight chain, branched or cyclic alkoxy group having from 1 to 6 carbon atoms, a halogen atom, a nitro group, an amino group, a hydroxyl group, or a cyano group; R<sub>4</sub> represents a substituted or unsubstituted aryl group, or a substituted or unsubstituted cycloalkyl group having from 3 to 15 carbon atoms; m represents a natural number of from 1 to 4.

13. (original):The positive radiation-sensitive composition as claimed in claim 4, wherein the resin (a) is a resin in which 5 to 45 mol% of an entire phenolic hydroxyl groups in an alkali-soluble resin are protected with an acid-decomposable group represented by the formula (II).

14. (original):The positive radiation-sensitive composition as claimed in claim 1, wherein the resin (a) has a weight average molecular weight of from 3,000 to 80,000.

15. (original):The positive radiation-sensitive composition as claimed in claim 1, wherein the surfactant (c) contains at least one of a fluorine atom and a silicon atom.